LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1129IQ-3.3#TRPBF	**(Engineering Calculation)**	DDPAK
(printed on: 7/16/2011 12:20:04 PM)	**TOTAL MASS (g):**	**1.39819**

COMPONENT	**VENDOR/**	**CONSTITUENT**	**CAS**	**CONSTITUENT**	**CONSTITUENT**	**CONSTITUENT**
MATERIAL	**INDUSTRY NAMES**	**NAME**	**NUMBER**	**MASS (g)**	**(PPM) OF MATERIAL**	**(PPM) OF TOTAL PKG.**
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.002887**	**1000000**	**2064.812**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.852419	998500	609658.9
		Iron (Fe)	7439-89-6	0	0	0
		Phosporus (P)	7723-14-0	0	0	0
		Zinc (Zn)	7440-66-6	0	0	0
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0.001281	1500	916.1844
		Lead Frame Total:		**0.854981**	**1000000**	**611491.2**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.009978218	1000000	7136.524
		External Plating Total:		**0.009978218**	**1000000**	**7136.524**
		Inter. Plating Ni	7440-02-0	0.004	740740.8	2860.841
		Inter. Plating Ag	7440-22-4	0.0014	259259.3	1001.294
		Internal Plating Total:		**0.0054**	**1000000**	**3862.136**
Die Attach	95Pb / 5 Sn	Silver (Ag)	7440-22-4	0	0	0
		Tin (Sn)	7440-31-5	7.80E-05	50000	55.7864
		Lead (Pb)	7439-92-1	0.001478	950000	1057.081
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Antimony (Sb)	7440-36-0	0	0	0
		Resin (EP)		0	0	0
		Die Attach Total:		**0.001556**	**1000000**	**1112.867**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.053704	103000	38409.65
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.466653	895000	333755
		Antimony	1309-64-4	0	0	0
		Trioxide (Sb2O3)				
		Metal Hydroxid		0	0	0
		Carbon Black (C)	1333-86-4	0.001043	2000	745.9644
		Encapsulation Total:		**0.5214**	**1000000**	**372910.7**
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.001988**	**1000000**	**1421.838**
Estimated						
				TOTAL MASS (g):		**1.39819**